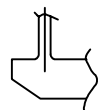
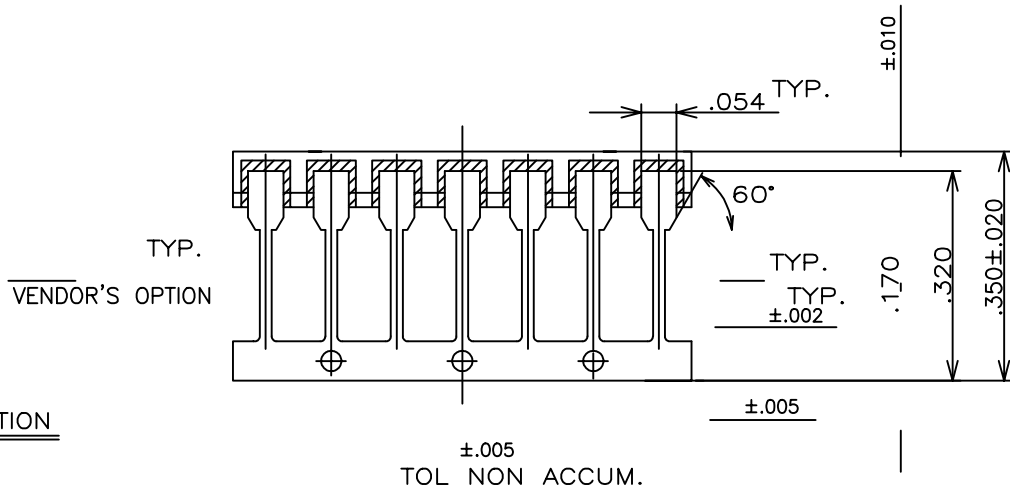


DETAIL-A

NOTES :

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 0.20HM MAX.



VENDOR'S OPTION

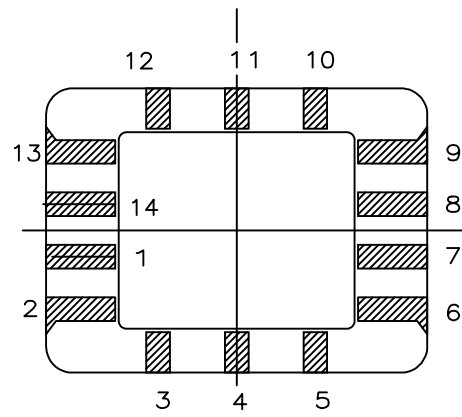
VENDOR'S OPTION

SB014K290-1				S=0
				D=0
DRAWN	CHECKED	APPROVED	DATE	
H.K	K.M		JUN.19.'80	
DRAWING NO.				SHEET
KD-80290-A				1/2

MODIFICATION						NAME	TOLERANCE
						14 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED
						SCALE 5/1	±.005
						MATERIAL AS INDICATED	THIRD ANGLE PROJECTION
△	REDRAWN (CONVERTED CAD DATA)	OCT.15.'93	S.F	T.C/K.M	T.A	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		


TYP.

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BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE	
						14 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.F	T.C	K.M	T.A	OCT.15.93
						SCALE 10/1	MATERIAL					
							THIRD ANGLE PROJECTION					
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET	
								KD-80290-A			2/2	